



# SMG10N65

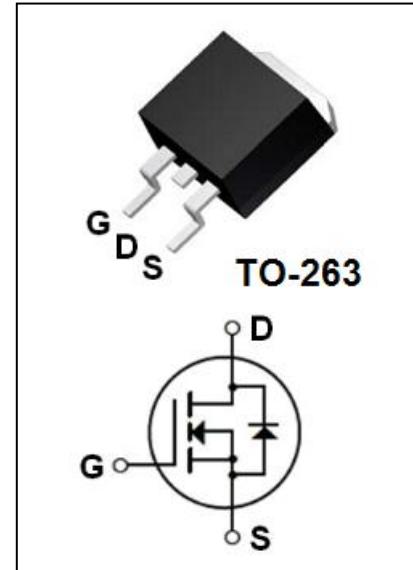
650V N-Channel MOSFET

## ● Features:

- 10.0A, 650V,  $R_{DS(on)(Typ)} = 0.80\Omega$  @  $V_{GS}=10V$
- Low Gate Charge
- Low  $C_{rss}$
- 100% Avalanche Tested
- Fast Switching
- Improved dv/dt Capability

## ● Application:

- High Frequency Switching Mode Power Supply
- Active Power Factor Correction



## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	650	V
$I_D$	Drain Current - Continuous ( $T_c=25^\circ C$ )	10.0*	A
	- Continuous ( $T_c=100^\circ C$ )	6.3*	A
$I_{DM}$	Drain Current - Pulsed (Note1)	40*	A
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Limit Reference Value) (Note2)	632	mJ
$I_{AR}$	Avalanche Current (Note1)	10.0	A
$E_{AR}$	Repetitive Avalanche Energy (Note1)	16.8	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ (Note3)	4.5	V/ns
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	167	W
	-Derate above $25^\circ C$	1.33	W/ $^\circ C$
$T_j$	Operating Junction Temperature	150	$^\circ C$
$T_{stg}$	Storage Temperature Range	-55 to +150	$^\circ C$

\* Drain Current Limited by Maximum Junction Temperature.

## Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.75	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	$^\circ C/W$

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### Electrical Characteristics(Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditons	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-source Breakdown Voltage	V <sub>GS</sub> =0V ,I <sub>D</sub> =250μA	650	--	--	V
△BV <sub>DSS</sub> /△T <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> =250μA (Referenced to 25°C)	--	0.68	--	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V	--	--	1	μA
		V <sub>DS</sub> =520V,Tc=125°C	--	--	10	μA
I <sub>GSSF</sub>	Gate-Body Leakage Current,Forward	V <sub>GS</sub> =+30V, V <sub>DS</sub> =0V	--	--	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current,Reverse	V <sub>GS</sub> =-30V, V <sub>DS</sub> =0V	--	--	-100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	--	4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10 V, I <sub>D</sub> =5.0A	--	0.80	1.05	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =20 V, I <sub>D</sub> =5.0A (Note4)	--	8.5	--	S
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V,V <sub>GS</sub> =0V, f=1.0MHz	--	1510	--	pF
C <sub>oss</sub>	Output Capacitance		--	125	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	7	--	pF
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 325 V, I <sub>D</sub> = 10 A, R <sub>G</sub> = 25 Ω (Note4,5)	--	19.3	--	ns
t <sub>r</sub>	Turn-On Rise Time		--	94	--	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	131	--	ns
t <sub>f</sub>	Turn-Off Fall Time		--	73	--	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 520 V, I <sub>D</sub> =10 A, V <sub>GS</sub> = 10 V (Note4,5)	--	38	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	7.3	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	17.4	--	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>s</sub>	Maximum Continuous Drain-Source Diode Forward Current	--	--	10	--	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current	--	--	40	--	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> =0V,I <sub>s</sub> =10.0 A	--	--	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> =0V, I <sub>s</sub> =10.0 A, d I <sub>F</sub> /dt=100A/μs (Note4)	--	368	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	3.40	--	μC

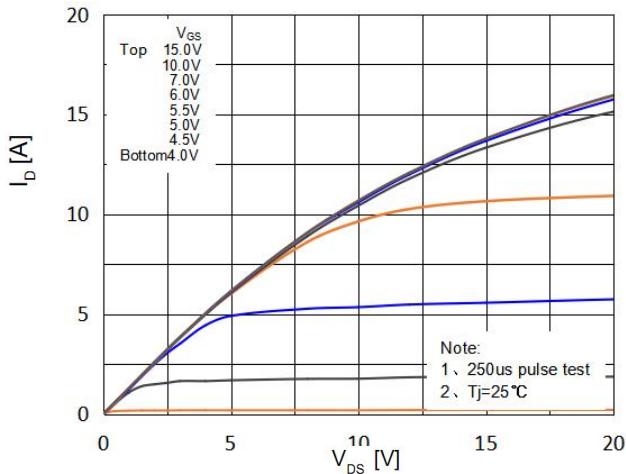
Notes:

- 1、Repetitive Rating:Pulse Width Limited by Maximum Junction Temperature.
- 2、L = 11.5mH, I<sub>AS</sub> =10.0A, V<sub>DD</sub> =100V, R<sub>G</sub> = 25 Ω, Starting T<sub>J</sub> = 25°C.
- 3、I<sub>SD</sub>≤10.0A, di/dt≤200A/μs, V<sub>DD</sub>≤BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C.
- 4、Pulse Test : Pulse Width ≤300 μ s, Duty Cycle≤2%.
- 5、Essentially Independent of Operating Temperature.

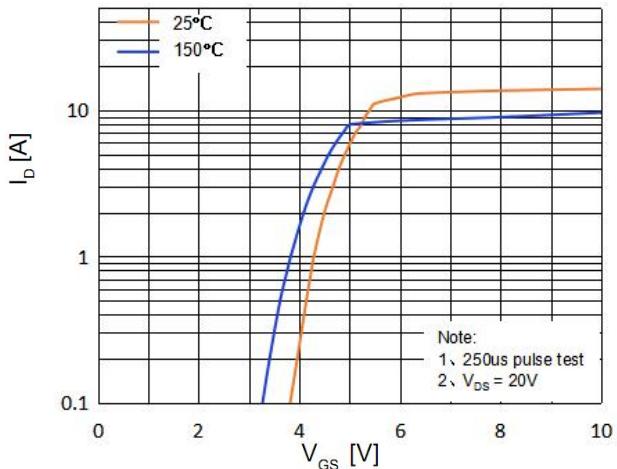
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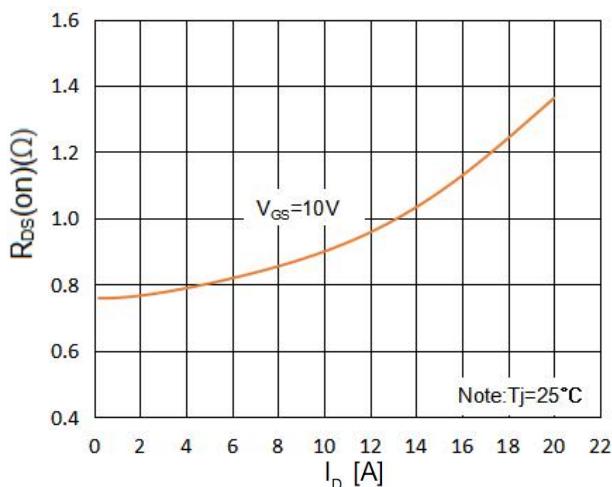
### On-Region Characteristics



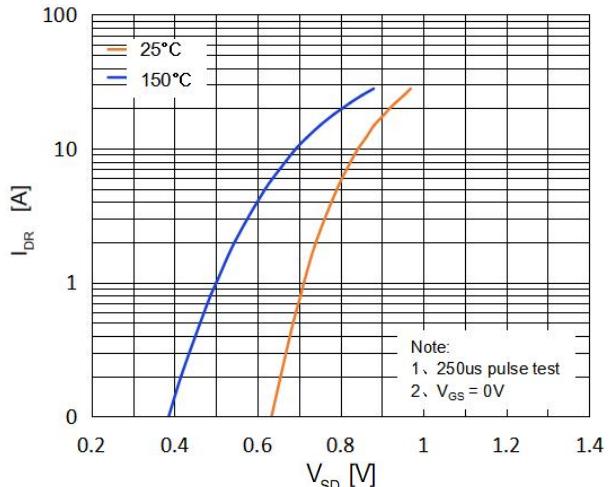
### Transfer Characteristics



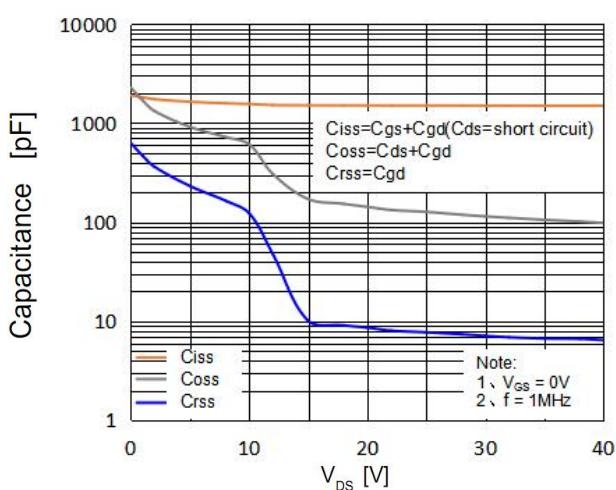
### On-Resistance Variation vs. Drain Current and Gate Voltage



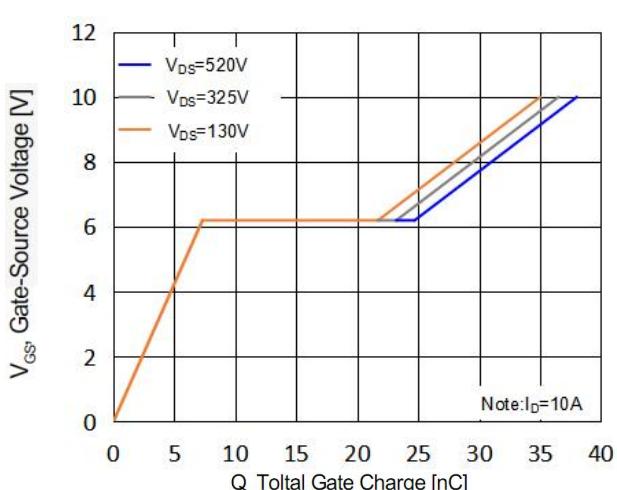
### Body Diode Forward Voltage Variation vs. Source Current and Temperature



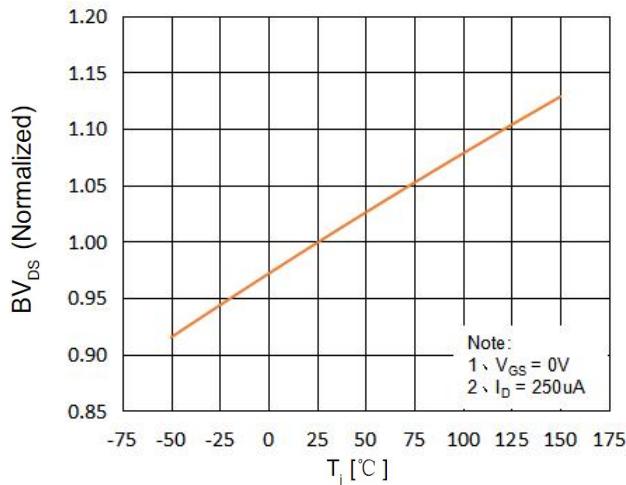
### Capacitance Characteristics



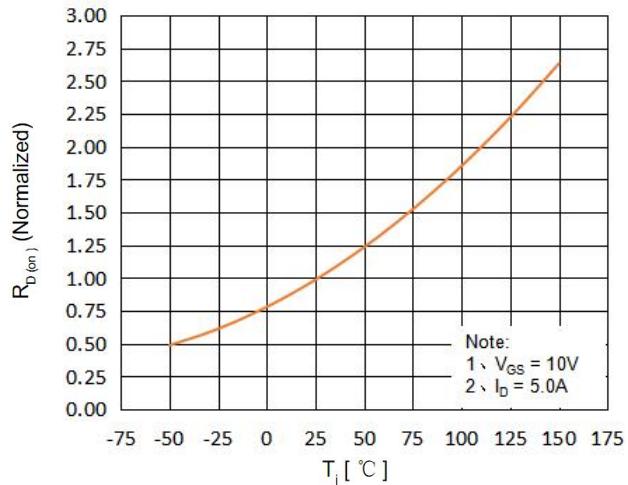
### Gate Charge Characteristics



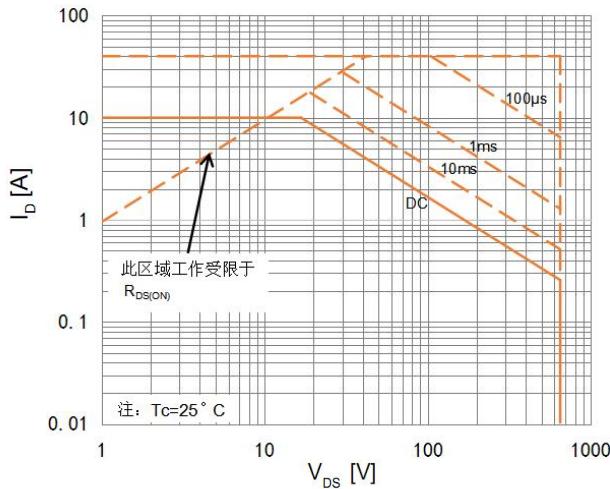
### Breakdown Voltage Variation vs. Temperature



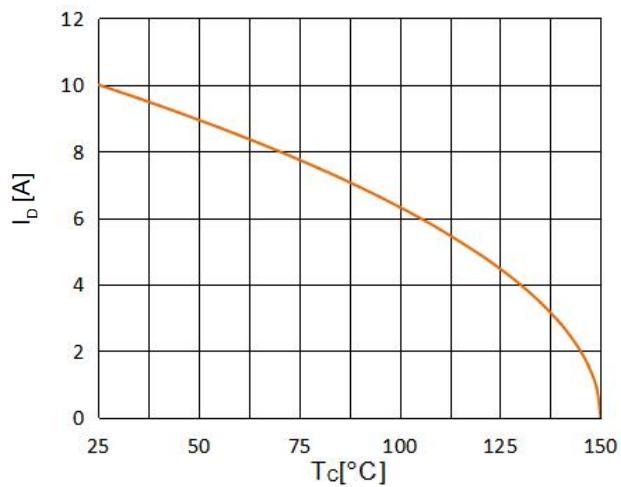
### On-Resistance Variation vs. Temperature



### Maximum Safe Operating Area



### Maximum Drain Current Vs. Case Temperature



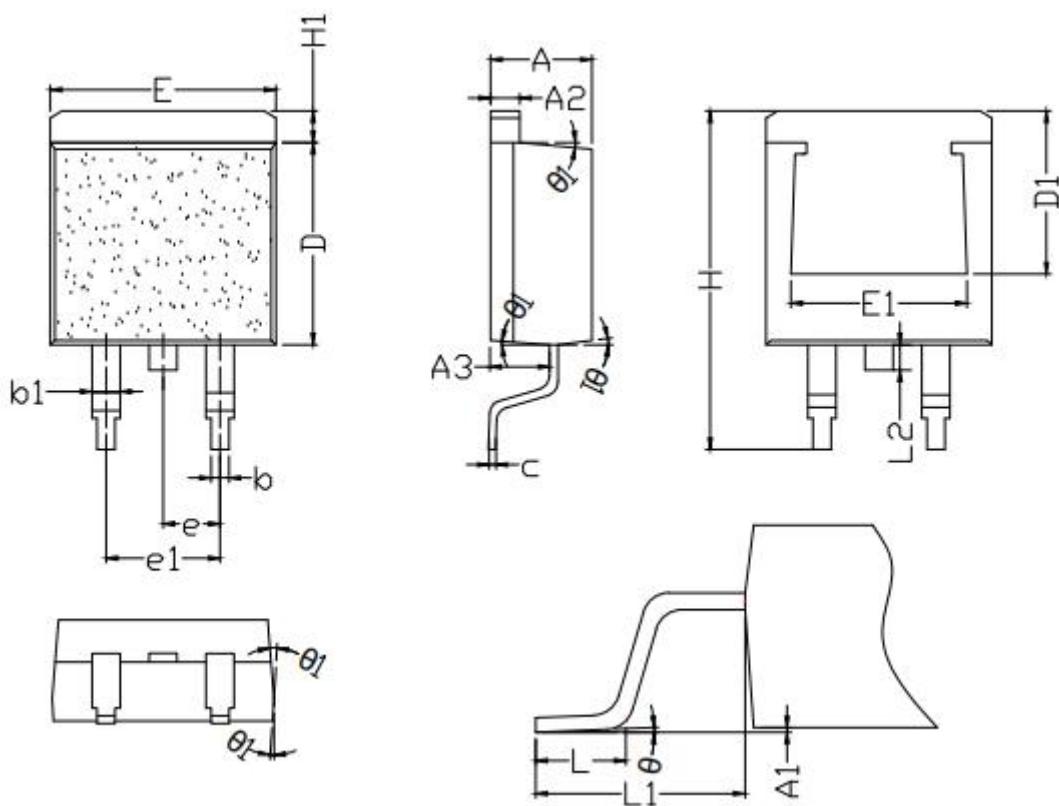
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**TO-263 Package Dimensions**

UNIT: mm

SYMBOL	min	nom	max	SYMBOL	min	nom	max
A	4.32	4.52	4.72	E1		7.85REF	
A1	0.00	0.10	0.20	e		2.54REF	
A2	1.17	1.27	1.37	e1		5.08REF	
A3	2.45	2.60	2.75	H	14.70	15.10	15.50
b	0.70	0.80	0.90	H1	1.10	1.30	1.50
b1	1.18	1.28	1.38	L	1.80	2.25	2.70
c	0.30	0.38	0.46	L1	4.45	4.75	5.05
D	8.70	8.95	9.20	L2	1.10	1.30	1.50
D1		7.25REF		θ	0°	2°	5°
E	9.82	10.07	10.32	θ1	3°	-	9°





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注意事项：

- 1、在电路设计时请不要超过器件的最大额定值，否则会影响整机的可靠性。
- 2、MOSFET产品为静电敏感型器件，使用时应注意采取防静电保护措施，如佩戴防静电手环、设备接地等。
- 3、如需安装散热片，请注意控制扭力大小及散热片的平整度。
- 4、该规格书由华科公司制作，并可能不定期更改，恕不另行通知。
- 5、如有疑问，请及时联系我司销售代表。

版本履历表：

序号	版本号	修改时间	修改记录
1	V1.0	2022-12-20	首次发行